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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	22
Program Memory Size	7KB (4K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 6x12b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc773t-i-ss

TABLE 1-1 PIC16C773 PINOUT DESCRIPTION

Pin Name	DIP, SSOP, SOIC Pin#	I/O/P Type	Buffer Type	Description
OSC1/CLKIN	9	I	ST/CMOS(3)	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	10	O	—	Oscillator crystal output. Connects to crystal or resonator in crystal oscillator mode. In RC mode, the OSC2 pin outputs CLKOUT which has 1/4 the frequency of OSC1, and denotes the instruction cycle rate.
$\overline{MCLR}$/VPP	1	I/P	ST	Master clear (reset) input or programming voltage input. This pin is an active low reset to the device.
				PORTA is a bi-directional I/O port.
RA0/AN0	2	I/O	TTL	RA0 can also be analog input0
RA1/AN1	3	I/O	TTL	RA1 can also be analog input1
RA2/AN2/VREF-/VRL	4	I/O	TTL	RA2 can also be analog input2 or negative analog reference voltage input or internal voltage reference low
RA3/AN3/VREF+/VRH	5	I/O	TTL	RA3 can also be analog input3 or positive analog reference voltage input or internal voltage reference high
RA4/T0CKI	6	I/O	ST	RA4 can also be the clock input to the Timer0 module. Output is open drain type.
				PORTB is a bi-directional I/O port. PORTB can be software programmed for internal weak pull-up on all inputs.
RB0/INT	21	I/O	TTL/ST(1)	RB0 can also be the external interrupt pin.
RB1/$\overline{SS}$	22	I/O	TTL/ST(1)	RB1 can also be the SSP slave select
RB2/AN8	23	I/O	TTL	RB2 can also be analog input8
RB3/AN9/LVDIN	24	I/O	TTL	RB3 can also be analog input9 or the low voltage detect input reference
RB4	25	I/O	TTL	Interrupt on change pin.
RB5	26	I/O	TTL	Interrupt on change pin.
RB6	27	I/O	TTL/ST(2)	Interrupt on change pin. Serial programming clock.
RB7	28	I/O	TTL/ST(2)	Interrupt on change pin. Serial programming data.
				PORTC is a bi-directional I/O port.
RC0/T1OSO/T1CKI	11	I/O	ST	RC0 can also be the Timer1 oscillator output or Timer1 clock input.
RC1/T1OSI/CCP2	12	I/O	ST	RC1 can also be the Timer1 oscillator input or Capture2 input/ Compare2 output/PWM2 output.
RC2/CCP1	13	I/O	ST	RC2 can also be the Capture1 input/Compare1 output/PWM1 output.
RC3/SCK/SCL	14	I/O	ST	RC3 can also be the synchronous serial clock input/output for both SPI and I^2C modes.
RC4/SDI/SDA	15	I/O	ST	RC4 can also be the SPI Data In (SPI mode) or data I/O (I^2C mode).
RC5/SDO	16	I/O	ST	RC5 can also be the SPI Data Out (SPI mode).
RC6/TX/CK	17	I/O	ST	RC6 can also be the USART Asynchronous Transmit or Synchronous Clock.
RC7/RX/DT	18	I/O	ST	RC7 can also be the USART Asynchronous Receive or Synchronous Data.
AVSS	8	P		Ground reference for A/D converter
AVDD	7	P		Positive supply for A/D converter
VSS	19	P	—	Ground reference for logic and I/O pins.
VDD	20	P	—	Positive supply for logic and I/O pins.

Legend: I = input O = output I/O = input/output P = power
— = Not used TTL = TTL input ST = Schmitt Trigger input

Note 1: This buffer is a Schmitt Trigger input when configured for the multiplexed function.
2: This buffer is a Schmitt Trigger input when used in serial programming mode.
3: This buffer is a Schmitt Trigger input when configured in RC oscillator mode and a CMOS input otherwise.

TABLE 1-2 PIC16C774 PINOUT DESCRIPTION

Pin Name	DIP Pin#	PLCC Pin#	QFP Pin#	I/O/P Type	Buffer Type	Description
OSC1/CLKIN	13	14	30	I	ST/CMOS(4)	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	14	15	31	O	—	Oscillator crystal output. Connects to crystal or resonator in crystal oscillator mode. In RC mode, OSC2 pin outputs CLKOUT which has 1/4 the frequency of OSC1, and denotes the instruction cycle rate.
$\overline{MCLR}$/VPP	1	2	18	I/P	ST	Master clear (reset) input or programming voltage input. This pin is an active low reset to the device.
						PORTA is a bi-directional I/O port.
RA0/AN0	2	3	19	I/O	TTL	RA0 can also be analog input0
RA1/AN1	3	4	20	I/O	TTL	RA1 can also be analog input1
RA2/AN2/VREF-/VRL	4	5	21	I/O	TTL	RA2 can also be analog input2 or negative analog reference voltage input or internal voltage reference low
RA3/AN3/VREF+/VRH	5	6	22	I/O	TTL	RA3 can also be analog input3 or positive analog reference voltage input or internal voltage reference high
RA4/T0CKI	6	7	23	I/O	ST	RA4 can also be the clock input to the Timer0 timer/counter. Output is open drain type.
RA5/AN4	7	8	24	I/O	TTL	RA5 can also be analog input4
						PORTB is a bi-directional I/O port. PORTB can be software programmed for internal weak pull-up on all inputs.
RB0/INT	33	36	8	I/O	TTL/ST(1)	RB0 can also be the external interrupt pin.
RB1/$\overline{SS}$	34	37	9	I/O	TTL/ST(1)	RB1 can also be the SSP slave select
RB2/AN8	35	38	10	I/O	TTL	RB2 can also be analog input8
RB3/AN9/LVDIN	36	39	11	I/O	TTL	RB3 can also be analog input9 or input reference for low voltage detect
RB4	37	41	14	I/O	TTL	Interrupt on change pin.
RB5	38	42	15	I/O	TTL	Interrupt on change pin.
RB6	39	43	16	I/O	TTL/ST(2)	Interrupt on change pin. Serial programming clock.
RB7	40	44	17	I/O	TTL/ST(2)	Interrupt on change pin. Serial programming data.

Legend: I = input O = output I/O = input/output P = power
— = Not used TTL = TTL input ST = Schmitt Trigger input

Note 1: This buffer is a Schmitt Trigger input when configured for the multiplexed function.
2: This buffer is a Schmitt Trigger input when used in serial programming mode.
3: This buffer is a Schmitt Trigger input when configured as general purpose I/O and a TTL input when used in the Parallel Slave Port mode (for interfacing to a microprocessor bus).
4: This buffer is a Schmitt Trigger input when configured in RC oscillator mode and a CMOS input otherwise.

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NOTES:

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2.2.2.4 PIE1 REGISTER

This register contains the individual enable bits for the peripheral interrupts.

Note: Bit PEIE (INTCON<6>) must be set to enable any peripheral interrupt.

FIGURE 2-6: PIE1 REGISTER (ADDRESS 8Ch)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PSPIE(1)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

bit 7: **PSPIE(1):** Parallel Slave Port Read/Write Interrupt Enable bit
1 = Enables the PSP read/write interrupt
0 = Disables the PSP read/write interrupt

bit 6: **ADIE**: A/D Converter Interrupt Enable bit
1 = Enables the A/D interrupt
0 = Disables the A/D interrupt

bit 5: **RCIE**: USART Receive Interrupt Enable bit
1 = Enables the USART receive interrupt
0 = Disables the USART receive interrupt

bit 4: **TXIE**: USART Transmit Interrupt Enable bit
1 = Enables the USART transmit interrupt
0 = Disables the USART transmit interrupt

bit 3: **SSPIE**: Synchronous Serial Port Interrupt Enable bit
1 = Enables the SSP interrupt
0 = Disables the SSP interrupt

bit 2: **CCP1IE**: CCP1 Interrupt Enable bit
1 = Enables the CCP1 interrupt
0 = Disables the CCP1 interrupt

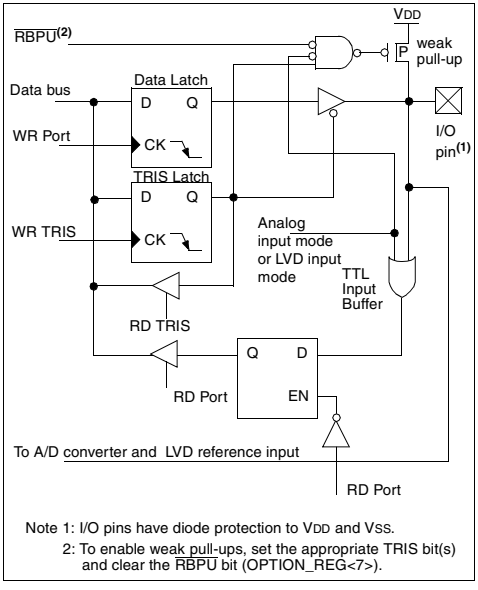
bit 1: **TMR2IE**: TMR2 to PR2 Match Interrupt Enable bit
1 = Enables the TMR2 to PR2 match interrupt
0 = Disables the TMR2 to PR2 match interrupt

bit 0: **TMR1IE**: TMR1 Overflow Interrupt Enable bit
1 = Enables the TMR1 overflow interrupt
0 = Disables the TMR1 overflow interrupt

Note 1: PSPIE is reserved on the 28-pin devices, always maintain this bit clear.

The RB3 pin is multiplexed with analog channel 9 and the low voltage detect input (RB3/AN9/LVDIN)

FIGURE 3-7: BLOCK DIAGRAM OF RB3/AN9/LVDIN PIN



Note 1: I/O pins have diode protection to VDD and VSS.
2: To enable weak pull-ups, set the appropriate TRIS bit(s) and clear the RBPU bit (OPTION_REG<7>).

Four of PORTB's pins, RB7:RB4, have an interrupt on change feature. Only pins configured as inputs can cause this interrupt to occur (i.e. any RB7:RB4 pin configured as an output is excluded from the interrupt on change comparison). The input pins (of RB7:RB4) are compared with the old value latched on the last read of PORTB. The "mismatch" outputs of RB7:RB4 are OR'ed together to generate the RB Port Change Interrupt with flag bit RBIF (INTCON<0>).

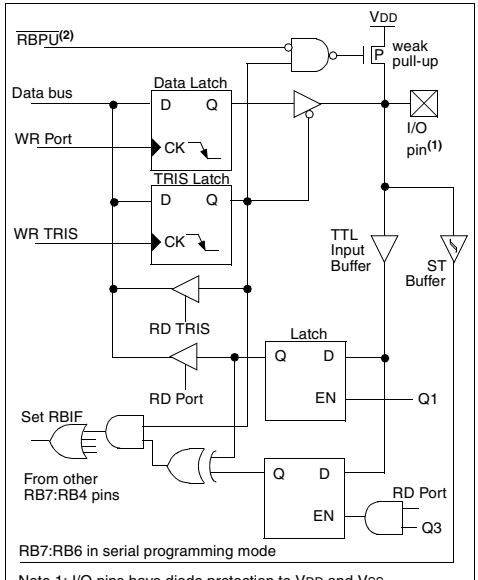
This interrupt can wake the device from SLEEP. The user, in the interrupt service routine, can clear the interrupt in the following manner:

a) Any read or write of PORTB. This will end the mismatch condition.
b) Clear flag bit RBIF.

A mismatch condition will continue to set flag bit RBIF. Reading PORTB will end the mismatch condition, and allow flag bit RBIF to be cleared.

The interrupt on change feature is recommended for wake-up on key depression operation and operations where PORTB is only used for the interrupt on change feature. Polling of PORTB is not recommended while using the interrupt on change feature.

FIGURE 3-8: BLOCK DIAGRAM OF RB7:RB4 PINS



Note 1: I/O pins have diode protection to VDD and VSS.
2: To enable weak pull-ups, set the appropriate TRIS bit(s) and clear the RBPU bit (OPTION_REG<7>).

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TABLE 3-3 PORTB FUNCTIONS

Name	Bit#	Buffer	Function
RB0/INT	bit0	TTL/ST(1)	Input/output pin or external interrupt input. Internal software programmable weak pull-up.
RB1/$\overline{SS}$	bit1	TTL/ST(3)	Input/output pin or SSP slave select. Internal software programmable weak pull-up.
RB2/AN8	bit2	TTL	Input/output pin or analog input8. Internal software programmable weak pull-up.
RB3/AN9/LVDIN	bit3	TTL	Input/output pin or analog input9 or Low-voltage detect input. Internal software programmable weak pull-up.
RB4	bit4	TTL	Input/output pin (with interrupt on change). Internal software programmable weak pull-up.
RB5	bit5	TTL	Input/output pin (with interrupt on change). Internal software programmable weak pull-up.
RB6	bit6	TTL/ST(2)	Input/output pin (with interrupt on change). Internal software programmable weak pull-up. Serial programming clock.
RB7	bit7	TTL/ST(2)	Input/output pin (with interrupt on change). Internal software programmable weak pull-up. Serial programming data.

Legend: TTL = TTL input, ST = Schmitt Trigger input

Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.
2: This buffer is a Schmitt Trigger input when used in serial programming mode.
3: This buffer is a Schmitt Trigger input when used as the SSP slave select.

TABLE 3-4 SUMMARY OF REGISTERS ASSOCIATED WITH PORTB

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
06h, 106h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx 11xx	uuuu 11uu
86h, 186h	TRISB	PORTB Data Direction Register								1111 1111	1111 1111
81h, 181h	OPTION_REG	$\overline{RBPU}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
9Fh	ADCON1	ADFM	VCFG2	VCFG1	VCFG0	PCFG3	PCFG2	PCFG1	PCFG0	0000 0000	0000 0000

Legend: x = unknown, u = unchanged. Shaded cells are not used by PORTB.

8.1 SPI Mode

The SPI mode allows 8-bits of data to be synchronously transmitted and received simultaneously. All four modes of SPI are supported. To accomplish communication, typically three pins are used:

- Serial Data Out (SDO)
- Serial Data In (SDI)
- Serial Clock (SCK)

Additionally, a fourth pin may be used when in a slave mode of operation:

- Slave Select ($\overline{SS}$)

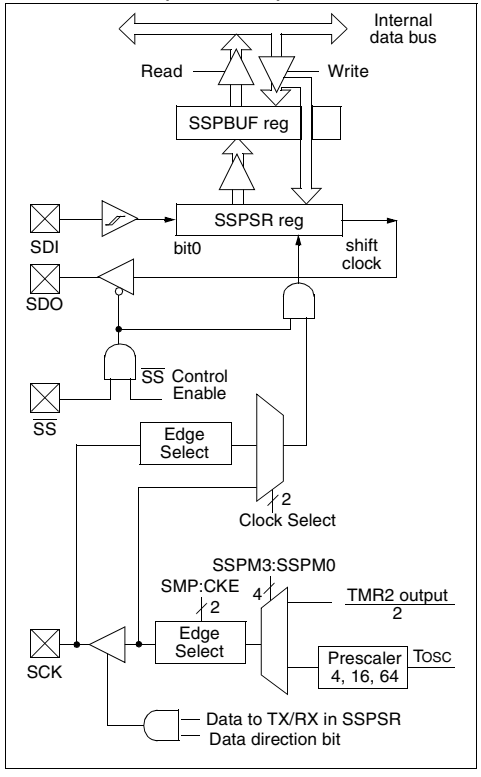
8.1.1 OPERATION

When initializing the SPI, several options need to be specified. This is done by programming the appropriate control bits (SSPCON<5:0> and SSPSTAT<7:6>). These control bits allow the following to be specified:

- Master Mode (SCK is the clock output)
- Slave Mode (SCK is the clock input)
- Clock Polarity (Idle state of SCK)
- Data input sample phase (middle or end of data output time)
- Clock edge (output data on rising/falling edge of SCK)
- Clock Rate (Master mode only)
- Slave Select Mode (Slave mode only)

Figure 8-4 shows the block diagram of the MSSP module when in SPI mode.

FIGURE 8-4: MSSP BLOCK DIAGRAM (SPI MODE)



The MSSP consists of a transmit/receive Shift Register (SSPSR) and a buffer register (SSPBUF). The SSPSR shifts the data in and out of the device, MSb first. The SSPBUF holds the data that was written to the SSPSR, until the received data is ready. Once the 8-bits of data have been received, that byte is moved to the SSPBUF register. Then the buffer full detect bit BF (SSPSTAT<0>) and the interrupt flag bit SSPIF (PIR1<3>) are set. This double buffering of the received data (SSPBUF) allows the next byte to start reception before reading the data that was just received. Any write to the SSPBUF register during transmission/reception of data will be ignored, and the write collision detect bit WCOL (SSPCON<7>) will be set. User software must clear the WCOL bit so that it can be determined if the following write(s) to the SSPBUF register completed successfully.

When the application software is expecting to receive valid data, the SSPBUF should be read before the next byte of data to transfer is written to the SSPBUF. Buffer full bit, BF (SSPSTAT<0>), indicates when the SSPBUF has been loaded with the received data (transmission is complete). When the SSPBUF is read, bit BF is cleared. This data may be irrelevant if the SPI is only a transmitter. Generally the MSSP Interrupt is used to

8.2 MSSP I²C Operation

The MSSP module in I²C mode fully implements all master and slave functions (including general call support) and provides interrupts on start and stop bits in hardware to determine a free bus (multi-master function). The MSSP module implements the standard mode specifications as well as 7-bit and 10-bit addressing.

Refer to Application Note AN578, *"Use of the SSP Module in the I²C Multi-Master Environment."*

A "glitch" filter is on the SCL and SDA pins when the pin is an input. This filter operates in both the 100 kHz and 400 kHz modes. In the 100 kHz mode, when these pins are an output, there is a slew rate control of the pin that is independant of device frequency.

FIGURE 8-10: I²C SLAVE MODE BLOCK DIAGRAM

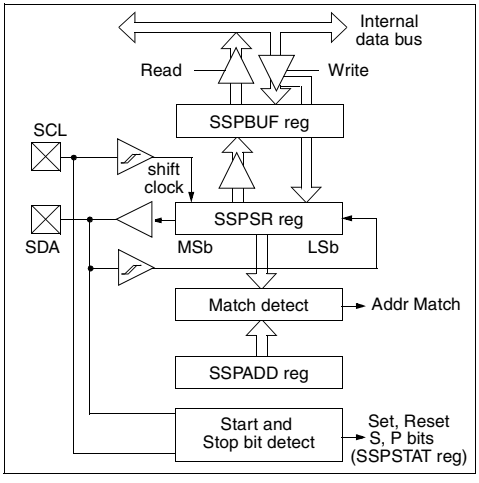
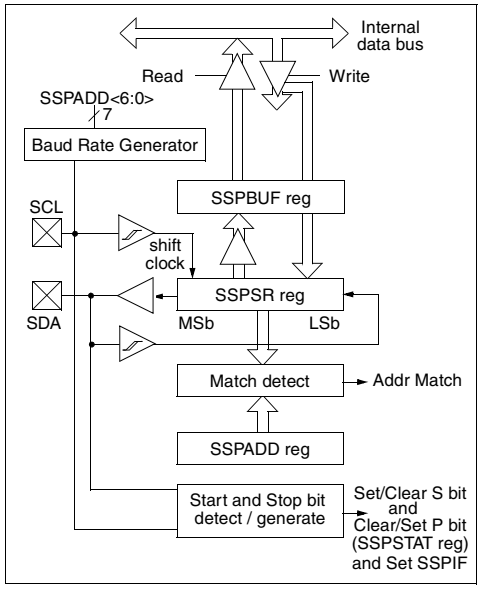


FIGURE 8-11: I²C MASTER MODE BLOCK DIAGRAM



Two pins are used for data transfer. These are the SCL pin, which is the clock, and the SDA pin, which is the data. The SDA and SCL pins that are automatically configured when the I²C mode is enabled. The SSP module functions are enabled by setting SSP Enable bit SSPEN (SSPCON<5>).

The MSSP module has six registers for I²C operation. They are the:

- SSP Control Register (SSPCON)
- SSP Control Register2 (SSPCON2)
- SSP Status Register (SSPSTAT)
- Serial Receive/Transmit Buffer (SSPBUF)
- SSP Shift Register (SSPSR) - Not directly accessible
- SSP Address Register (SSPADD)

The SSPCON register allows control of the I²C operation. Four mode selection bits (SSPCON<3:0>) allow one of the following I²C modes to be selected:

- I²C Slave mode (7-bit address)
- I²C Slave mode (10-bit address)
- I²C Master mode, clock = OSC/4 (SSPADD +1)

Before selecting any I²C mode, the SCL and SDA pins must be programmed to inputs by setting the appropriate TRIS bits. Selecting an I²C mode, by setting the SSPEN bit, enables the SCL and SDA pins to be used as the clock and data lines in I²C mode.

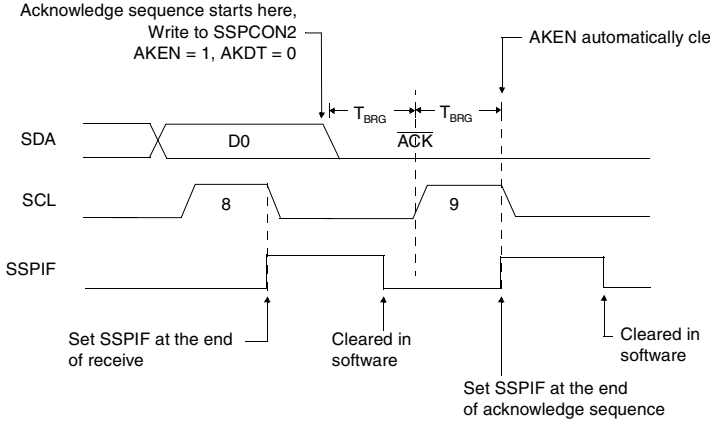
8.2.13 ACKNOWLEDGE SEQUENCE TIMING

An acknowledge sequence is enabled by setting the acknowledge sequence enable bit, AKEN (SSPCON2<4>). When this bit is set, the SCL pin is pulled low and the contents of the acknowledge data bit is presented on the SDA pin. If the user wishes to generate an acknowledge, then the AKDT bit should be cleared. If not, the user should set the AKDT bit before starting an acknowledge sequence. The baud rate generator then counts for one rollover period (T_{BRG}), and the SCL pin is de-asserted (pulled high). When the SCL pin is sampled high (clock arbitration), the baud rate generator counts for T_{BRG} . The SCL pin is then pulled low. Following this, the AKEN bit is automatically cleared, the baud rate generator is turned off, and the SSP module then goes into IDLE mode. (Figure 8-29)

8.2.13.13 WCOL STATUS FLAG

If the user writes the SSPBUF when an acknowledege sequence is in progress, then WCOL is set and the contents of the buffer are unchanged (the write doesn't occur).

FIGURE 8-29: ACKNOWLEDGE SEQUENCE WAVEFORM



Note: T_{BRG}= one baud rate generator period.

9.1 USART Baud Rate Generator (BRG)

The BRG supports both the Asynchronous and Synchronous modes of the USART. It is a dedicated 8-bit baud rate generator. The SPBRG register controls the period of a free running 8-bit timer. In asynchronous mode bit BRGH (TXSTA<2>) also controls the baud rate. In synchronous mode bit BRGH is ignored. Table 9-1 shows the formula for computation of the baud rate for different USART modes which only apply in master mode (internal clock).

Given the desired baud rate and Fosc, the nearest integer value for the SPBRG register can be calculated using the formula in Table 9-1. From this, the error in baud rate can be determined.

Example 9-1 shows the calculation of the baud rate error for the following conditions:

FOSC = 16 MHz
Desired Baud Rate = 9600
BRGH = 0
SYNC = 0

EXAMPLE 9-1: CALCULATING BAUD RATE ERROR

Desired Baud rate = Fosc / (64 (X + 1))

9600 = 16000000 /(64 (X + 1))

X = ⌊25.042⌋ = 25

Calculated Baud Rate=16000000 / (64 (25 + 1))

= 9615

$$\text{Error} = \frac{\text{(Calculated Baud Rate - Desired Baud Rate)}}{\text{Desired Baud Rate}}$$

= (9615 - 9600) / 9600

= 0.16%

It may be advantageous to use the high baud rate (BRGH = 1) even for slower baud clocks. This is because the FOSC/(16(X + 1)) equation can reduce the baud rate error in some cases.

Writing a new value to the SPBRG register causes the BRG timer to be reset (or cleared). This ensures the BRG does not wait for a timer overflow before outputting the new baud rate.

9.1.1 SAMPLING

The data on the RC7/RX/DT pin is sampled three times by a majority detect circuit to determine if a high or a low level is present at the RX pin.

TABLE 9-1 BAUD RATE FORMULA

SYNC	BRGH = 0 (Low Speed)	BRGH = 1 (High Speed)
0	(Asynchronous) Baud Rate = FOSC/(64(X+1))	Baud Rate= FOSC/(16(X+1))
1	(Synchronous) Baud Rate = FOSC/(4(X+1))	NA

X = value in SPBRG (0 to 255)

TABLE 9-2 REGISTERS ASSOCIATED WITH BAUD RATE GENERATOR

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
98h	TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010
18h	RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x	0000 000x
99h	SPBRG	Baud Rate Generator Register								0000 0000	0000 0000

Legend: x = unknown, - = unimplemented read as '0'. Shaded cells are not used by the BRG.

TABLE 12-6 INITIALIZATION CONDITIONS FOR ALL REGISTERS (Cont.'d)

Register	Devices		Power-on Reset, Brown-out Reset	MCLR Resets WDT Reset	Wake-up via WDT or Interrupt
TRISA	773	774	---1 1111	---1 1111	---u uuuu
	773	774	--11 1111	--11 1111	--uu uuuu
TRISB	773	774	1111 1111	1111 1111	uuuu uuuu
TRISC	773	774	1111 1111	1111 1111	uuuu uuuu
TRISD	773	774	1111 1111	1111 1111	uuuu uuuu
TRISE	773	774	0000 -111	0000 -111	uuuu -uuu
PIE1	773	774	r000 0000	r000 0000	ruuu uuuu
	773	774	0000 0000	0000 0000	uuuu uuuu
PIE2	773	774	0--- 0--0	0--- 0--0	u--- u--u
PCON	773	774	---- --qq	---- --uu	---- --uu
PR2	773	774	1111 1111	1111 1111	1111 1111
SSPADD	773	774	0000 0000	0000 0000	uuuu uuuu
SSPSTAT	773	774	0000 0000	0000 0000	uuuu uuuu
TXSTA	773	774	0000 -010	0000 -010	uuuu -uuu
SPBRG	773	774	0000 0000	0000 0000	uuuu uuuu
REFCON	773	774	0000 ----	0000 ----	uuuu ----
LVDCON	773	774	--00 0101	--00 0101	--uu uuuu
ADRESL	773	774	xxxx xxxx	uuuu uuuu	uuuu uuuu
ADCON1	773	774	0000 000	0000 0000	uuuu uuuu

Legend: u = unchanged, x = unknown, - = unimplemented bit, read as '0', q = value depends on condition

Note 1: One or more bits in INTCON, PIR1 and/or PIR2 will be affected (to cause wake-up).

2: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

3: See Table 12-5 for reset value for specific condition.

FIGURE 12-7: TIME-OUT SEQUENCE ON POWER-UP (MCLR TIED TO VDD)

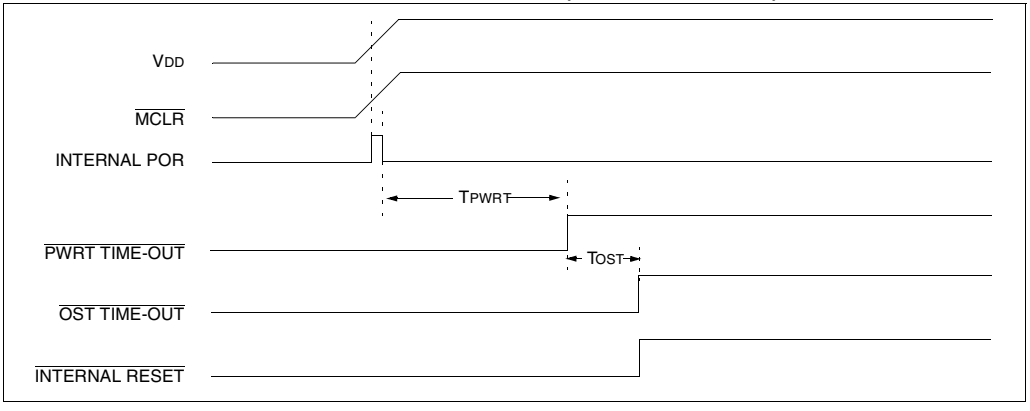


TABLE 14-1 DEVELOPMENT TOOLS FROM MICROCHIP

		PIC12C5XX	PIC14000	PIC16C5X	PIC16CXXX	PIC16C6X	PIC16C7XX	PIC16C8X	PIC16C9XX	PIC17C4X	PIC17C7XX	24CXX 25CXX 93CXX	HCS200 HCS300 HCS301
Emulator Products	MPLAB™-ICE	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓		
	ICEPIC™ Low-Cost In-Circuit Emulator			✓	✓	✓	✓	✓	✓				
Software Tools	MPLAB™ Integrated Development Environment	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓		
	MPLAB™ C17* Compiler									✓	✓		
	*fuzzy*TECH®-MP Explorer/Edition Fuzzy Logic Dev. Tool	✓	✓	✓	✓	✓	✓	✓	✓	✓			
	Total Endurance™ Software Model											✓	
Programmers	PICSTART® Plus Low-Cost Universal Dev. Kit	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓		
	PRO MATE® II Universal Programmer	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
	KEELOQ® Programmer												✓
Demo Boards	SEEVAL® Designers Kit											✓	
	SIMICE	✓		✓									
	PICDEM-14A		✓										
	PICDEM-1			✓	✓			✓		✓			
	PICDEM-2					✓	✓						
	PICDEM-3								✓				
	KEELOQ® Evaluation Kit												✓
	KEELOQ Transponder Kit												✓

DC CHARACTERISTICS		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial Operating voltage VDD range as described in DC spec Section 15.1 and Section 15.2.					
Param No.	**Characteristic**	**Sym**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	Output High Voltage						
D090	I/O ports (Note 3)	VOH	VDD - 0.7	—	—	V	IOH = -3.0 mA, VDD = 4.5V, -40°C to +85°C
D092	OSC2/CLKOUT (RC osc config)		VDD - 0.7	—	—	V	IOH = -1.3 mA, VDD = 4.5V, -40°C to +85°C
D150*	**Open-Drain High Voltage**	VOD	—	—	8.5	V	RA4 pin
	Capacitive Loading Specs on Output Pins						
D100	OSC2 pin	COSC2	—	—	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1.
D101	All I/O pins and OSC2 (in RC	CIO	—	—	50	pF	
D102	mode) SCL, SDA in I^2C mode	CB	—	—	400	pF	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C77X be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

PRELIMINARY

15.5.2 TIMING DIAGRAMS AND SPECIFICATIONS

FIGURE 15-4: EXTERNAL CLOCK TIMING

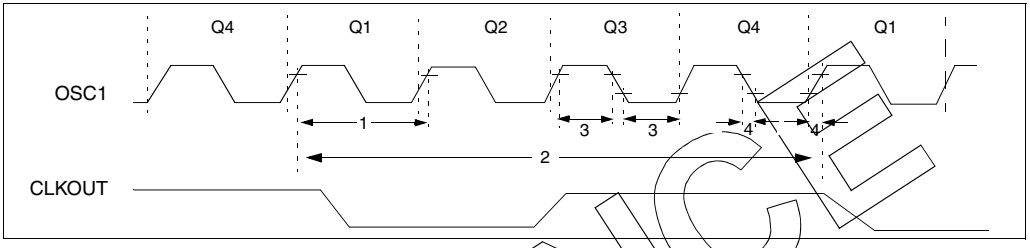


TABLE 15-5 EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	Fosc	**External CLKIN Frequency (Note 1)**	DC	—	4	MHz	XT and RC osc mode
			DC	—	4	MHz	HS osc mode (-04)
			DC	—	20	MHz	HS osc mode (-20)
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency (Note 1)	DC	—	4	MHz	RC osc mode
			0.1	—	4	MHz	XT osc mode
			4	—	20	MHz	HS osc mode
			5	—	200	kHz	LP osc mode
1	Tosc	**External CLKIN Period (Note 1)**	250	—	—	ns	XT and RC osc mode
			250	—	—	ns	HS osc mode (-04)
			50	—	—	ns	HS osc mode (-20)
			5	—	—	µs	LP osc mode
		Oscillator Period (Note 1)	250	—	—	ns	RC osc mode
			250	—	10,000	ns	XT osc mode
			250	—	250	ns	HS osc mode (-04)
			50	—	250	ns	HS osc mode (-20)
			5	—	—	µs	LP osc mode
2	TCY	**Instruction Cycle Time (Note 1)**	200	TCY	DC	ns	TCY = 4/FOSC
3*	TosL, TosH	**External Clock in (OSC1) High or Low Time**	100	—	—	ns	XT oscillator
			2.5	—	—	µs	LP oscillator
			15	—	—	ns	HS oscillator
4*	TosR, TosF	**External Clock in (OSC1) Rise or Fall Time**	—	—	25	ns	XT oscillator
			—	—	50	ns	LP oscillator
			—	—	15	ns	HS oscillator

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

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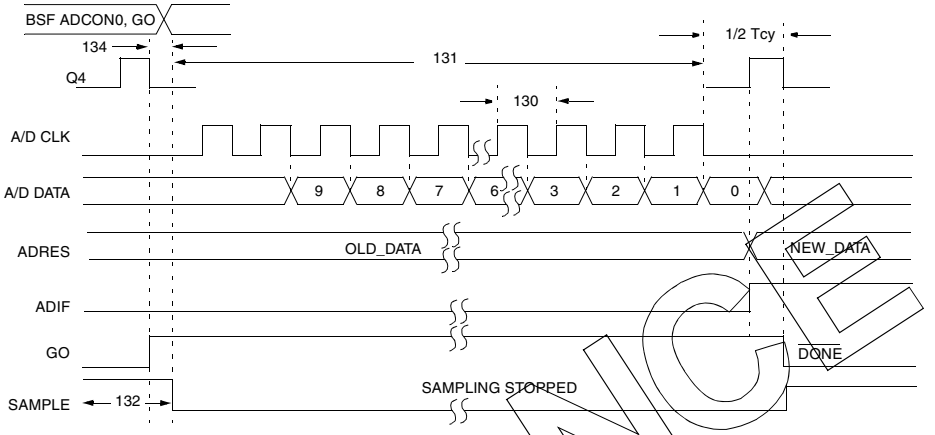
FIGURE 15-9: A/D CONVERSION TIMING (NORMAL MODE)



Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

TABLE 15-10 A/D CONVERSION REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
130*	TAD	A/D clock period	1.6	—	—	µs	Tosc based, VREF ≥ 2.5V
			3.0	—	—	µs	Tosc based, VREF full range
130*	TAD	A/D Internal RC oscillator period					ADCS1:ADCS0 = 11 (RC mode)
			3.0	6.0	9.0	µs	At VDD = 2.5V
			2.0	4.0	6.0	µs	At VDD = 5.0V
131*	TCNV	Conversion time (not including acquisition time) (Note 1)	—	13TAD	—	TAD	Set GO bit to new data in A/D result register
132*	TACQ	Acquisition Time	Note 2	11.5	—	µs	
			5*	—	—	µs	The minimum time is the amplifier settling time. This may be used if the "new" input voltage has not changed by more than 1LSb (i.e 1mV @ 4.096V) from the last sampled voltage (as stated on CHOLD).
134*	TGO	Q4 to A/D clock start	—	TOSC/2	—	—	If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: ADRES register may be read on the following TCY cycle.

2: See Section 11.6 for minimum conditions.

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FIGURE 15-12: CAPTURE/COMPARE/PWM TIMINGS (CCP1 AND CCP2)

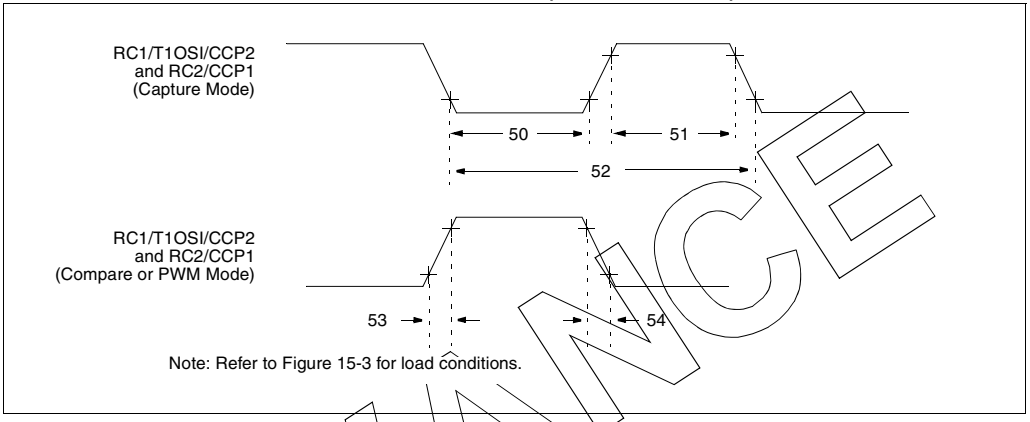

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TABLE 15-13 CAPTURE/COMPARE/PWM REQUIREMENTS (CCP1 AND CCP2)

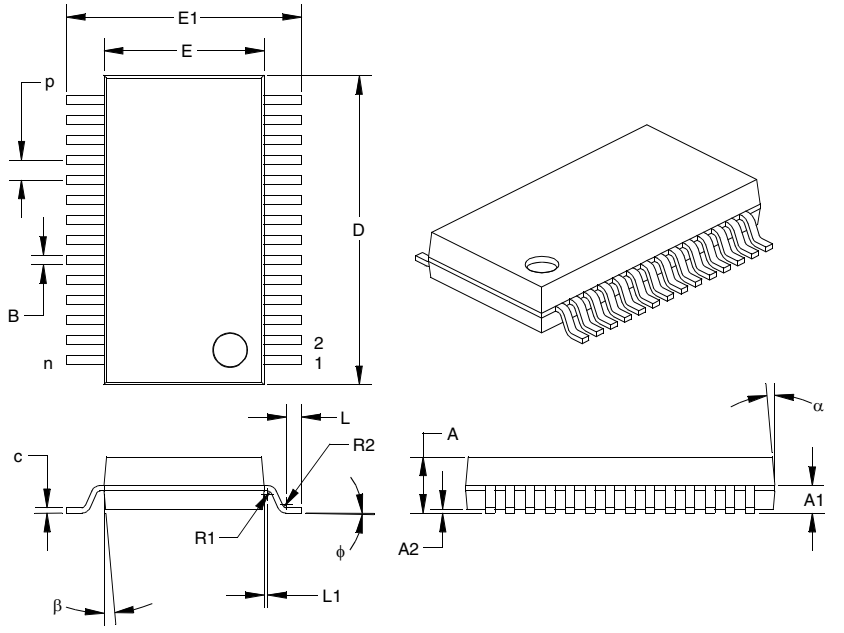
Parameter No.	Sym	Characteristic			Min	Typ†	Max	Units	Conditions
50*	TccL	CCP1 and CCP2 input low time	No Prescaler		0.5TCY + 20	—	—	ns	
			With Prescaler	PIC16**C**77X	10	—	—	ns	
				PIC16**LC**77X	20	—	—	ns	
51*	TccH	CCP1 and CCP2 input high time	No Prescaler		0.5TCY + 20	—	—	ns	
			With Prescaler	PIC16**C**77X	10	—	—	ns	
				PIC16**LC**77X	20	—	—	ns	
52*	TccP	CCP1 and CCP2 input period			$\frac{3T_{CY} + 40}{N}$	—	—	ns	N = prescale value (1,4 or 16)
53*	TccR	CCP1 and CCP2 output fall time		PIC16**C**77X	—	10	25	ns	
				PIC16**LC**77X	—	25	45	ns	
54*	TccF	CCP1 and CCP2 output fall time		PIC16**C**77X	—	10	25	ns	
				PIC16**LC**77X	—	25	45	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

17.5 K04-073 28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES			MILLIMETERS*		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Pitch	p		0.026			0.65	
Number of Pins	n		28			28	
Overall Pack. Height	A	0.068	0.073	0.078	1.73	1.86	1.99
Shoulder Height	A1	0.026	0.036	0.046	0.66	0.91	1.17
Standoff	A2	0.002	0.005	0.008	0.05	0.13	0.21
Molded Package Length	D‡	0.396	0.402	0.407	10.07	10.20	10.33
Molded Package Width	E‡	0.205	0.208	0.212	5.20	5.29	5.38
Outside Dimension	E1	0.301	0.306	0.311	7.65	7.78	7.90
Shoulder Radius	R1	0.005	0.005	0.010	0.13	0.13	0.25
Gull Wing Radius	R2	0.005	0.005	0.010	0.13	0.13	0.25
Foot Length	L	0.015	0.020	0.025	0.38	0.51	0.64
Foot Angle	ϕ	0	4	8	0	4	8
Radius Centerline	L1	0.000	0.005	0.010	0.00	0.13	0.25
Lead Thickness	c	0.005	0.007	0.009	0.13	0.18	0.22
Lower Lead Width	B†	0.010	0.012	0.015	0.25	0.32	0.38
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter.

† Dimension “B” does not include dam-bar protrusions. Dam-bar protrusions shall not exceed 0.003” (0.076 mm) per side or 0.006” (0.152 mm) more than dimension “B.”

‡ Dimensions “D” and “E” do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010” (0.254 mm) per side or 0.020” (0.508 mm) more than dimensions “D” or “E.”

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BIT/REGISTER CROSS-REFERENCE LIST

ADCS1:ADCS0 ..... ADCON0<7:6>
ADIE ..... PIE1<6>
ADIF ..... PIR1<6>
ADON ..... ADCON0<0>
BF ..... SSPSTAT<0>
$\overline{BOR}$ ..... PCON<0>
BRGH ..... TXSTA<2>
C ..... STATUS<0>
CCP1IE ..... PIE1<2>
CCP1IF ..... PIR1<2>
CCP1M3:CCP1M0 ..... CCP1CON<3:0>
CCP1X:CCP1Y ..... CCP1CON<5:4>
CCP2IE ..... PIE2<0>
CCP2IF ..... PIR2<0>
CCP2M3:CCP2M0 ..... CCP2CON<3:0>
CCP2X:CCP2Y ..... CCP2CON<5:4>
CHS2:CHS0 ..... ADCON0<5:3>
CKE ..... SSPSTAT<6>
CKP ..... SSPCON<4>
CREN ..... RCSTA<4>
CSRC ..... TXSTA<7>
D/$\overline{A}$ ..... SSPSTAT<5>
DC ..... STATUS<1>
FERR ..... RCSTA<2>
GIE ..... INTCON<7>
GO/$\overline{DONE}$ ..... ADCON0<2>
IBF ..... TRISE<7>
IBOV ..... TRISE<5>
INTE ..... INTCON<4>
INTEDG ..... OPTION_REG<6>
INTF ..... INTCON<1>
IRP ..... STATUS<7>
OBF ..... TRISE<6>
OERR ..... RCSTA<1>
P ..... SSPSTAT<4>
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$\overline{PD}$ ..... STATUS<3>
PEIE ..... INTCON<6>
$\overline{POR}$ ..... PCON<1>
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PSA ..... OPTION_REG<3>
PSPIE ..... PIE1<7>
PSPIF ..... PIR1<7>
PSPMODE ..... TRISE<4>
R/$\overline{W}$ ..... SSPSTAT<2>
RBIE ..... INTCON<3>
RBIF ..... INTCON<0>
$\overline{RBPU}$ ..... OPTION_REG<7>
RCIE ..... PIE1<5>
RCIF ..... PIR1<5>
RP1:RP0 ..... STATUS<6:5>
RX9 ..... RCSTA<6>
RX9D ..... RCSTA<0>
S ..... SSPSTAT<3>
SMP ..... SSPSTAT<7>
SPEN ..... RCSTA<7>
SREN ..... RCSTA<5>
SSPEN ..... SSPCON<5>
SSPIE ..... PIE1<3>
SSPIF ..... PIR1<3>
SSPM3:SSPM0 ..... SSPCON<3:0>
SSPOV ..... SSPCON<6>
SYNC ..... TXSTA<4>
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T0IE ..... INTCON<5>
T0IF ..... INTCON<2>
T0SE ..... OPTION_REG<4>
T1CKPS1:T1CKPS0 ..... T1CON<5:4>
T1OSCEN ..... T1CON<3>
$\overline{T1SYNC}$ ..... T1CON<2>
T2CKPS1:T2CKPS0 ..... T2CON<1:0>
TMR1CS ..... T1CON<1>
TMR1IE ..... PIE1<0>
TMR1IF ..... PIR1<0>
TMR1ON ..... T1CON<0>
TMR2IE ..... PIE1<1>
TMR2IF ..... PIR1<1>
TMR2ON ..... T2CON<2>
$\overline{TO}$ ..... STATUS<4>
TOUTPS3:TOUTPS0 ..... T2CON<6:3>
TRMT ..... TXSTA<1>
TX9 ..... TXSTA<6>
TX9D ..... TXSTA<0>
TXEN ..... TXSTA<5>
TXIE ..... PIE1<4>
TXIF ..... PIR1<4>
UA ..... SSPSTAT<1>
WCOL ..... SSPCON<7>
Z ..... STATUS<2>

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